

TECHNIQUES FOR ATTACHING A HEAT SINK ASSEMBLY TO  
A CIRCUIT BOARD COMPONENT

ABSTRACT OF THE DISCLOSURE

5           A circuit board module has a circuit board, a component mounted to the circuit  
board, and a heat sink assembly. The heat sink assembly includes a base member  
having a first edge and a second edge. The base member is configured to operate as a  
thermal conduit between a first location proximate to the component and a second  
location distal to the component. The heat sink assembly further includes a first rail  
10 member coupled to the base member along the first edge of the base member, a second  
rail member coupled to the base member along the second edge of the base member, and  
an actuation mechanism coupled to the base member. The actuation mechanism is  
configured to move portions of the members toward each other when the base member  
resides at the first location to fasten the base member to the component.